European Network on New Sensing Technologies for Air Pollution Control and Environmental Sustainability - *EuNetAir* COST Action TD1105

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MULTI SENSOR PLATFORM FOR SMART BUILDING MANAGEMENT - PROGRESS AND ASPECTS OF NANOWIRE INTEGRATION



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Outline

- 1. Overview MCL
- 2. Overview MSP-Project
- 3. Metal Oxide Nanowires
 - 3.1 SnO₂-NWs
 - 3.2 CuO-NWs
- 4. Summary & Outlook



1. Overview MCL



Thin film and nanowire sensors

- SnO₂-thin films
- SnO₂-NWs (n-type)
- CuO-NWs (p-type)
- ZnO-NWs (n-type)

Target gases: CO, H₂, H₂S, O₃ CO₂, VOCs, NO₂ In dry and humid air







Single NW-devices (SnO₂, CuO, ZnO)





- CuO NW sensor fabricated by optical lithography
- 2-point measurement
- L ~ 6,5 μm, diameter ~120 nm
- CuO NW sensor fabricated by e-beam lithography
- 4-point measurement
- L ~ 900 nm, diameter ~ 50 nm



Multi NW-devices (SnO₂, CuO, ZnO)



 SnO₂ nanowires locally synthesized on 200 µm wide metal stripes



- Thermal oxidation at 400°C in ambient atmosphere for 1h
- ZnO NWs bridging the gaps





Integration on CMOS µhp (SnO₂ thin film, SnO₂, CuO, ZnO-NWs)



- Post processing
- Spray pyrolysis
- 50nm SnO_2 film ($T_{max} = 400^{\circ}C$)



- 500 nm Cu on CMOS Gap 2µm
- Thermal oxidation process on CMOS µhp
- 350°C for 1h in air (< 400°C!)</p>



2. Overview MSP Project

MSP - Multi Sensor Platform for Smart Building Management







Project No: 611887



- Platform chip as basic "LEGO[™]" building block for 3Dintegration to MSP Multi Sensor Systems
- Development of processes and technologies for 3Dintegration of sensors and devices
- "Other than CMOS compatible materials" (GaN, CNTs,...)





Target Parameters





IndoorsOutdoors $CO, CO_2, VOCs, PM$ $NO_2, O_3, CO, PM_{10}, PM_{2.5}, UFPs$





17 partners from 6 countries



MSP Concept & Objectives



- CMOS technology as sound foundation to ensure cost efficient mass fabrication
- Take-up of Key Enabling Technologies for new components and devices
- Integrating heterogeneous technologies for realization of smart systems





MSP-specific KETs: Nanotechnology

- APPS: SnO₂ film
- MCL: SnO₂ thin film + (SnO₂, CuO, ZnO)-NWs
- IMEC: GaN/AIGaN
- UCAM: Graphene & CNTs
- ALU-FR: (bi)metallic Nanoparticles
- UCL: Graphene
- UNIBS: SnO₂, CuO, ZnO, RuO-NWs





APPS: SnO₂ film



MCL: SnO₂ film & NWs











IMEC: GaN/AIGaN



UCAM: Graphene & CNTs









UCL: Graphene



UNIBS: Nanowires

- Vapour Phase Growth (PVD)
- Thermal Evaporation
- Thermal Oxidation
- Anodization







3. Metal Oxide Nanowires

- Versatile tools for many applications !
- Variety of materials (Si, III-V, polymers, CNTs, metal oxides,...)
- Different geometries (length, diameter, shape,...)





CuO







ZnO

 SnO_2







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Single crystalline,....





3.1 SnO₂-NW Gas Sensor

- Growth of NWs and harvesting in Isopropanol
- Transfer of SnO₂-NWs on SiO₂/Si-Substrate
- Spin coating of NW suspension
- Photolithography
- 200 nm Ti-Au + lift-off





Device fabrication

- Optical Lithography
- Spin coating of CuO NWs
- SEM imaging of NW
- Spin coating e-beam resist
- Writefield alignment
- E-beam exposure
- Metallization + lift-off





Single NW-devices





Problems ?

Yes ! Lot of problems with NWs concerning reproducibility and reliability!





- Reproducibility !
- Each device is a unique device !

Elise Brunet, PhD Thesis: "Fabrication of tin oxide nanowire gas sensors" (2014)







- Reproducibility !
- Each device is a unique device !







- Reproducibility !
- Each device is a unique device !







- Reproducibility !
- Each device is a unique device !







- Metal contacts !
- I-V characteristics (RT, no annealing)



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- Metal contacts !
- I-V characteristics (RT, annealing 5 min 400^oC)







- Metal contacts !
- I-V characteristics (200°C, annealing 5 min 400°C)





Problems 2



Figure 43: Distribution of resistance values of SnO₂ nanowires measured in a 2-point configuration at 200°C after annealing for different metal contacts. Each point represents the resistance of one nanowire with a linear I-V characteristic.



	no annealing	annealing 400°C	annealing 400°C
	room temperature	room temperature	200°C
I-V Characteristics	16	12	28
bad contact	1	0	0
diode	13	2	2
almost symmetric	2	8	13
linear	0	2	13

Temperature	90 ppm CO Response [%]	90 ppm CO Response [%]	
	d ~ 70 nm	d ~ 90 nm	
200°C	44	23	
250°C	42	27	
300°C	54	46	



Problems 3

Conductivity !

No clear correlation with diameter of NW (200°C)

Device name	R_{2pt} [M Ω]	${ m R}_{4pt}$ $[{ m M}\Omega]$	${ m R}_C$ [M Ω]	$\begin{array}{c} \mathbf{R}_C/\mathbf{R}_{2pt} \\ [\%] \end{array}$	Diameter [nm]	Conductivity [S/m]
NW-ebeam-1	180	87	93	52	60	2.0
NW-ebeam-2	56	38	18	33	65	4.0
NW-ebeam-3	112	47	64	58	75	2.4
NW-ebeam-4	97	67	30	31	75	1.7
NW-ebeam-5	42	18	24	57	80	5.6
NW-ebeam-6	3 0	14	16	54	150	2.0





Conductivity !

No clear correlation with diameter and length of NW



Problems 3

- 37 SnO₂ NW sensor investigated (2-point configuration)
- Length 1,4 5,2 μm
- Diameter 55 200 nm
- $\bullet~8$ nanowires present a conductivity at 200°C in the range 5-10 S/m,
- 15 in the range 20-100 S/m,
- 8 in the range 140-550 S/m,
- 6 in the range 850-2300 S/m.



Problems 4

Additional barriers and crystallographic orientation





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Figure 50: (a) HAADF image of NW-a. The positions A to F indicate the location where the EELS spectra have been measured. (b) Elemental mapping of NW-b: SnO_2 is represented in green, Ti in blue and SiO_x in red.

Different crystalline orientations of NWs



Table 8: Properties of the two nanowires investigated by FIB-TEM.

	NW-a	NW-b
Length $[\mu m]$	1.8	1.8
Diameter [nm]	70	70
Resistance at 200°C $[k\Omega]$	270	75000
Conductivity at $200^{\circ}C$ [S/m]	1730	6
Growth direction	[111]	[100]

More experiments required, but extremely time (and cost) consuming !



3.2 CuO-NW Gas Sensor

- Evaporated Pt metallization layer
- Annealing at T=400°C for 30 min
- 2-point measurement
- Strong variation of conductivity (factor 5) !





Electrical Characterization

- Conductivity of 10 NW devices tested
- No significant correlations with diameter or length of NW!





Figure 6.4: Transport parameters of single CuO nanowires (two-point configuration)

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TEM reveals twinning defect



Figure 6.7: Cross-sectional transmission electron microscopy of Ni/Au contacts



NPs on SnO₂-NW for sensor optimization

- Au, AuPd, AuPt, PtPd
- Interface? Long term stability? etc.





4. Summary & Outlook

NWs are very useful components for gas sensor devices !

Very good for basic characterization

Single NW-Devices are problematic:

- Reproducibility
- Metal contacts
- Conductivity
- Different crystal growth directions
- Control is extremely difficult !



Multi-NW approach

- Numerous NWs with different diameter and length
- Statistic helps to "average" properties



Multi-NW approach

- Numerous NWs with different diameter and length
- Statistic helps to "average" properties





- Integration on CMOS feasible 400°C (CuO, ZnO)
- Transfer processes have to be developed (SnO₂)





Need for R&D projects dedicated to reliability issues of NW-based (gas) sensor devices !





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Functional Integrated nanoSystems

1st International Conference *nano* FIS 2014 Functional Integrated *nano* Systems

3 – 5 December 2014, Graz/Austria

nanoFIS 2014 contributes to European Micro- & Nanoelectronics and increases visibility in particular in the More-Than-Moore domain.



nano FIS 2014 will highlight latest R&D results in the following Topics:

- Session A ADVANCED FUNCTIONAL MATERIALS
- Session B NANOSENSORS
- Session C SYSTEM INTEGRATION & PACKAGING
- Session D RELIABILITY
- Session E INNOVATIVE MANUFACTURING PROCESSES

PANEL DISCUSSION

"Airbus of Chips - Feasible European Reality or Science Fiction?"

Panel Leader

- Michael Wiesmüller, Austrian Federal Ministry for Transport, Innovation and Technology (Austria)

Panelists

- Willy van Puymbroeck, European Commission (Belgium)
- Jong Min Kim, University of Oxford (United Kingdom)
- Zhong Lin Wang, Georgia Institute of Technology (USA)
- Martin Schrems, ams AG (Austria)
- Livio Baldi, Micron Semiconductors Italia (Italy)

Key Note Speakers:

Jong Min Kim University of Oxford, Professor of Electrical Engineering, Dept of Engineering Science, Fellow of St. Hughes College, Oxford (United Kingdom)



Mervi Paulasto-Kröckel

Aalto University, Electronics Integration and Reliability, School of Electrical Engineering, Aalto (Finland)

> Lars Samuelson Lund University, Solid State Physics and the Nanometer Structure Consortium, Lund (Sweden)





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